

Title (en)
LIQUID-PHASE DIFFUSION BONDING ALLOY FOIL FOR HEAT-RESISTANT MATERIAL WHICH IS JOINABLE IN OXIDIZING ATMOSPHERE

Title (de)
FLÜSSIG-PHASENDIFFUSIONSGEBUNDENE LEGIERUNGSFOLIE FÜR WÄRMEBESTÄNDIGES MATERIAL DAS IN OXIDIERUNG VERBINBAR IST

Title (fr)
FEUILLE D'ALLIAGE DE SOUDURE PAR DIFFUSION EN PHASE LIQUIDE POUR MATERIAU RESISTANT A LA CHALEUR POUVANT ETRE SOUDE EN ATMOSPHERE OXYDANTE

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Application
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Priority
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• JP 5940694 A 19940329

Abstract (en)
Alloy foils for liquid-phase diffusion bonding of heat-resisting metals in an oxidizing atmosphere comprise 6.0 to 15.0 percent silicon, 0.1 to 2.0 percent manganese, 0.50 to 30.0 percent chromium, 0.10 to 5.0 percent molybdenum, 0.50 to 10.0 percent vanadium, 0.02 to 1.0 percent niobium, 0.10 to 5.0 percent tungsten, 0.01 to 0.5 percent nitrogen, 0.10 to 5.0 percent boron, plus 0.005 to 1.0 percent carbon, and/or either or both of 0.01 to 5.0 percent titanium and 0.01 to 5.0 percent zirconium, all by mass, with the balance comprising nickel and impurities, and have a thickness of 3.0 to 300 μ m. Alloy foils for liquid-phase diffusion bonding of heat-resisting metals in an oxidizing atmosphere are also available with substantially vitreous structures. <IMAGE>

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Cited by
AU2002214472B2; US6303015B1; WO0131085A3; WO0238327A1; US7285151B2; US9513071B2; US9513072B2; US9702641B2; US9919385B2; WO02090038A1; EP2666582B1

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